

Trench IGBT Modules

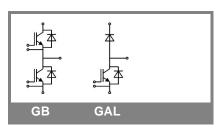
SKM 200GB176D SKM 200GAL176D

Features

- Homogeneous Si
- Trench = Trenchgate technology
- V_{CEsat} with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I_c

Typical Applications*

- AC inverter drives mains 575 -750 V AC
- Public transport (auxiliary syst.)



Absolute	Maximum Ratings	T,	_c = 25 °C, unless otherwise sp	ecified		
Symbol	Conditions		Values	Units		
IGBT						
V_{CES}	T _j = 25 °C T _i = 150 °C		1700	V		
I _C	T _j = 150 °C	T _c = 25 °C	260	Α		
		T _c = 80 °C	180	Α		
I _{CRM}	I _{CRM} =2xI _{Cnom}		300	Α		
V_{GES}			± 20	V		
t _{psc}	V_{CC} = 1200 V; $V_{GE} \le 20$ V;	T _j = 125 °C	10	μs		
	V _{CES} < 1700 V					
Inverse [
I _F	T _j = 150 °C	$T_c = 25 ^{\circ}C$	210	Α		
		T _c = 80 °C	140	Α		
I _{FRM}	I _{FRM} =2xI _{Fnom}		300	Α		
I _{FSM}	$t_p = 10 \text{ ms; sin.}$	T _j = 150 °C	1100	Α		
Freewheeling Diode						
I _F	T _j = 150 °C	T_{case} = 25 °C	210	Α		
		T _{case} = 80 °C	140	Α		
I _{FRM}	I _{FRM} =2xI _{Fnom}		300	Α		
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	1100	Α		
Module			·	•		
I _{t(RMS)}			500	Α		
T _{vj}			- 40 + 150	°C		
T _{stg}			-40+125	°C		
V _{isol}	AC, 1 min.		4000	V		

Characteristics T _c =		25 °C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units
IGBT	-					
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_{C} = 6 \text{ mA}$		5,2	5,8	6,4	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C			3	mA
V_{CE0}		T _j = 25 °C		1	1,2	V
		T _j = 125 °C		0,9	1,1	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		6,7	8,3	mΩ
		T _j = 125°C		10	12	$m\Omega$
V _{CE(sat)}	I _{Cnom} = 150 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		2	2,45	V
		T _j = 125°C _{chiplev} .		2,4	2,9	V
C _{ies}				11,4		nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,55		nF
C _{res}				0,44		nF
Q_G	V _{GE} = -8V+15V			1200		nC
R _{Gint}	T _j = 25 °C			4,25		Ω
t _{d(on)}				360		ns
t _r	$R_{Gon} = 5 \Omega$	V _{CC} = 1200V		45		ns
E _{on}	D - 5 O	I _C = 150A		93 760		mJ
$t_{ m d(off)} \ t_{ m f}$	$R_{Goff} = 5 \Omega$	T _j = 125 °C V _{GE} = ± 15V		760 140		ns ns
Կ E _{off}		GE 1.00		58		mJ
	per IGBT	1			0,12	K/W
$R_{\text{th(j-c)}}$	heriggi				0,12	rv/ v v



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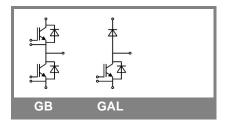
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Characteristics							
Symbol	Conditions		min.	typ.	max.	Units	
Inverse Diode							
$V_F = V_{EC}$	I _{Fnom} = 150 A; V _{GE} = 0 V			1,7	1,9	V	
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$		1,7	1,9	V	
V_{F0}		$T_j = 125 ^{\circ}\text{C}_{\text{chiplev.}}$ $T_j = 25 ^{\circ}\text{C}$		1,1	1,3	V	
		T _j = 125 °C		0,9	1,1	V	
r _F		T _j = 25 °C		4	4	mΩ	
		T _j = 125 °C		5,3	5,3	mΩ	
I _{RRM}	I _F = 150 A	T _j = 125 °C		195		Α	
Q_{rr}	di/dt = 3700 A/µs			52		μC	
E _{rr}	V _{GE} = -15 V; V _{CC} = 1200 \	/		31		mJ	
R _{th(j-c)D}	per diode				0,25	K/W	
FWD						•	
$V_F = V_{EC}$	I _{Fnom} = 150 A; V _{GE} = 0 V	$T_j = 25 ^{\circ}C_{\text{chiplev.}}$		1,7	1,9	V	
		$T_j = 125 ^{\circ}\text{C}_{\text{chiplev.}}$ $T_j = 25 ^{\circ}\text{C}$		1,7	1,9	V	
V _{F0}				1,1	1,3	V	
		$T_j = 125 ^{\circ}\text{C}$ $T_j = 25 ^{\circ}\text{C}$		0,9	1,1	V	
r _F				4	4	V	
		T _j = 125 °C T _j = 125 °C		5,3	5,3	V	
I _{RRM}	I _F = 150 A	T _j = 125 °C		195		Α	
Q_{rr}	di/dt = 3700 A/μs			52		μC	
E _{rr}	V _{GE} = -15 V; V _{CC} = 1200 \	/		31		mJ	
$R_{\text{th(j-c)FD}}$	per diode				0,25	K/W	
Module							
L _{CE}				15	20	nΗ	
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C		0,35		mΩ	
		T _{case} = 125 °C		0,5		mΩ	
R _{th(c-s)}	per module				0,038	K/W	
M _s	to heat sink M6		3		5	Nm	
M _t	to terminals M6		2,5		5	Nm	
w					325	g	

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





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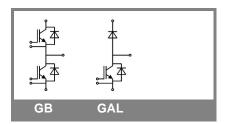
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Z _{th}					
Symbol	Conditions	Values	Units		
Z th(j-c)l R _i	i = 1	80	mk/W		
R _i	i = 2	30	mk/W		
R_i	i = 3	8,2	mk/W		
R_i	i = 4	1,8	mk/W		
tau _i	i = 1	0,0753	s		
tau _i	i = 2	0,01	s		
tau _i	i = 3	0,0008	S		
tau _i	i = 4	0,0003	s		
Z,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,					
Z R _i th(j-c)D	i = 1	160	mk/W		
R _i	i = 2	67	mk/W		
R_{i}	i = 3	20	mk/W		
R _i	i = 4	3	mk/W		
tau _i	i = 1	0,0382	s		
tau _i	i = 2	0,009	s		
tau _i	i = 3	0,0009	s		
tau _i	i = 4	0,005	s		

